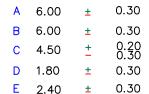
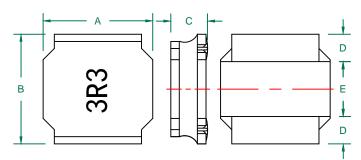
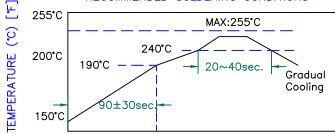
TYS60453R3N-10

PHYSICAL DIMENSIONS:

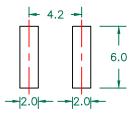


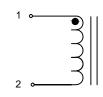


RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING

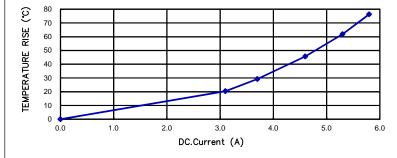




ELECTRICAL SPECIFICATION

	Min	Nom	Max
INDUCTANCE (uH) L @ 100KHz/1V ± 30%	2.31	3.30	4.29
DCR (Ω)		0.021	0.0273

CHARACTERISTICS OF TEMPERATURE RISE





Saturation Current(A)	5.90
SRF (MHz)	32
Temperature Rise Current (A)	3.70

CURRENT VS INDUCTANCE DROP IN RATES

0%							
-10%					<u> </u>		
-20%							
-30%							
√40% √50%							
<u> </u>							—
-60%							
-70%							
-80%							
-90%							
-100%	1	2	3	4	5	6	
			DC.Curren	it(A)			

NOTES:

- 1.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
- 3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
 A. AMBIENT TEMPERATURE: 20±15°C.
 B. RELATIVE HUMIDITY: 65%±20%.
- 4.SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF
 APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)
- 5. TEMPERATURE RISE CURRENT (IRMS):

DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

	DIMENSIONS ARE IN mm .			This print is the property of Laird Tech. and is loaned in confidence subject to return upon request a with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.	ind	Laird		
				PROJECT/PART NUMBER:	REV	PART TY		DRAWN BY:
С	CHANGE DIM C\D\E	01/28/16		TYS60453R3N-10	C		WER CTOR	QIU
В	CHANGE TEMP FROM&ADD CURVE	01/02/13	QIU	DATE: 12/07/12	CALE:	its	SHEET:	•
Α	ORIGINAL DRAFT	12/07/12	QIU		OOL #	. 13		
REV	DESCRIPTION	DATE	INT			~ - 1		of 1